

#### SMD3225 Series

### **Description**

Gas discharge tubes (GDT) use noble gasses enclosed in ceramic tubes to provide an alternate circuit path for voltage spikes. The ceramic envelope and with nickel connectors allow for high loads. SMD3225 Gas Discharge Tubes (GDT) series has a surge rating of 1kA, 8/20µs.Offered in a Squared Surface Mount package, which helps to make pick and place on PCB process easier.

This GDT series is perfectly suited for broadband equipment applications. The GDT's low off-state capacitance is compatible with high bandwidth applications and this capacitance loading value does not vary if the voltage across the GDT changes.

SMD3225 Gas Discharge Tube (GDT) series are specifically designed for protection of electrical, multimedia, and communication equipment against over voltage transients in surface mount assembly applications.



#### **Agency Approvals**

Agency	Standards	Certificate No.
c <b>Al</b> ®us	UL1449	E508408

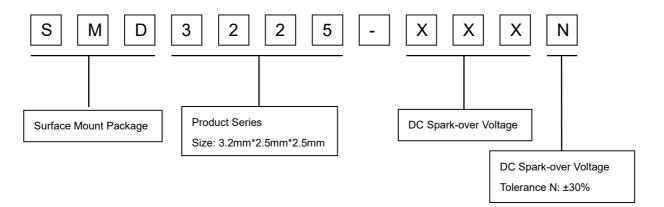
#### **Features**

- Excellent response to fast rising transients
- I Stable breakdown voltage
- I GHz working frequency
- I 8/20µs Impulse current capability: 1KA
- I Surface Mount package
- I Non-Radioactive
- I Ultra Low capacitance(<0.5pF) and insertion loss
- I Very Small Size: 3.2mm\*2.5mm\*2.5mm (EIA 1210)
- I Storage and operational temperature: -40~+85°C

## **Applications**

- I Communication equipment
- I CATV equipment
- I Test equipment
- I Data lines
- I Power supplies
- I Telecom SLIC protection
- I Broadband equipment
- ADSL equipment, including ADSL2+
- I XDSL equipment
- Satellite and CATV equipment
- I General telecom equipment

#### **Part Number Code**





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#### **Electrical Characteristics**

	DC Spark-over Voltage <sup>1) 2)</sup> @100V/S	Impulse Spark-over	Insulation		Glow	Arc Voltage	Life Ratings <sup>4)</sup>					
Part Number		Voltage		Capacitance			Impul		Alternating	Impulse Withstanding Voltage		
		100V/µS	1KV/µS	3)	@1MHz	@10mA	@1A	Discharge Current @8/20µS		Discharge Current @50Hz 1S	Capacity @10/700μS, 40W	Impulse Life @10/1000μS
		Max	Max	Min	Max	Typical	Typical	±5 times	1 time	5 times	±5 times	100 times
	v	v	٧	GΩ	pF	v	V	KA	KA	Α	κv	Α
SMD3225-075N	75±30%	500	600	1	0.5	60	10	1	1.5	1	6	10
SMD3225-090N	90±30%	500	600	1	0.5	60	10	1	1.5	1	6	10
SMD3225-150N	150±30%	500	600	1	0.5	60	10	1	1.5	1	6	10
SMD3225-200N	200±30%	600	700	1	0.5	60	10	1	1.5	1	6	10
SMD3225-230N	230±30%	600	700	1	0.5	60	10	1	1.5	1	6	10
SMD3225-300N	300±30%	700	800	1	0.5	60	10	1	1.5	1	6	10
SMD3225-350N	350±30%	750	850	1	0.5	60	10	1	1.5	1	6	10
SMD3225-400N	400±30%	800	900	1	0.5	135	15	1	1.5	1	6	10
SMD3225-470N	470±30%	850	950	1	0.5	135	15	1	1.5	1	6	10
SMD3225-600N	600±30%	900	1000	1	0.5	135	15	1	1.5	1	6	10
SMD3225-800N	800±30%	1200	1400	1	0.5	135	15	1	1.5	1	6	10
Glow to Arc transition Current												
Weight					~0.0	)95g						
Operation temperature -40~+85°C												
Recommended storage <sup>5)</sup>												
- Temperature					+35°C							
- Humidity												
- Period					≤ 2 years							
					40/85/21  Without							
• •						ad						
Moisture sensitivi	6)					te-tin plat	eu					

<sup>1)</sup> At delivery AQL 0.65 level II, DIN ISO 2859.

Terms and current waveforms in accordance with ITU-T K. 12, IEC61643-21 and IEC 61643-311.

<sup>&</sup>lt;sup>2)</sup> In ionized mode.

<sup>&</sup>lt;sup>3)</sup> Insulation Resistance Measuring Voltage: nominal voltage 75~150V at DC 50V, others at DC 100V.

<sup>&</sup>lt;sup>4)</sup> Tests according to ITU-T K.12 and UL 497B.

<sup>5)</sup> Specified in terms of corrosion against tin plating.

<sup>&</sup>lt;sup>6)</sup> Tests according to JEDEC J-STD-020.



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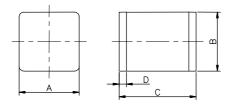
# **Certifications table**

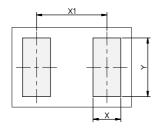
Part Number	<b>c 711</b> *us UL1449 E508408
SMD3225-075N	•
SMD3225-090N	•
SMD3225-150N	•
SMD3225-200N	•
SMD3225-230N	•
SMD3225-300N	•
SMD3225-350N	•
SMD3225-400N	•
SMD3225-470N	•
SMD3225-600N	•
SMD3225-800N	•

#### Notes:

- 1. indicates that the product has passed the certification.
- 2. -- indicates that the product is not certified.

### **Dimensions**





Recommended Soldering Pad Layout

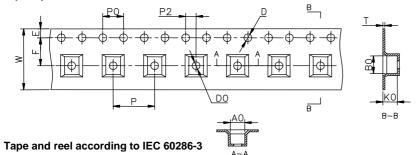
Symbol	Millimeters	Inches			
Α	2.5±0.2	0.098±0.008			
В	2.5±0.2	0.098±0.008			
С	3.2±0.3	0.126±0.012			
D	0.3±0.1	0.012±0.004			
х	1.3	0.051			
X1	3.3	0.130			
Y	2.8	0.110			



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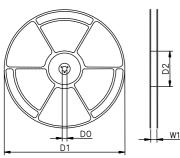
# **Packaging Information**

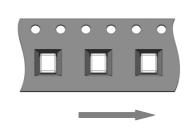
#### **Tape Specifications**



Symbol	Millimeters	Inches
w	12±0.3	0.472±0.012
A0	2.8±0.1	0.110±0.004
В0	3.5±0.1	0.138±0.004
K0	2.8±0.1	0.110±0.004
Р	8.0±0.1	0.315±0.004
F	5.5±0.1	0.217±0.004
E	1.75±0.1	0.069±0.004
D	1.5+0.1/-0.0	0.059+0.004/-0
P0	4±0.1	0.157±0.004
P2	2±0.1	0.079±0.004
Т	0.35±0.05	0.014±0.002
D0	13.3±0.15	0.524±0.006
D1	330±2	12.992±0.079
D2	100+1/-2	3.937+0.039/-0.
W1	12.5±0.4	0.492±0.016

### **Reel Specifications**





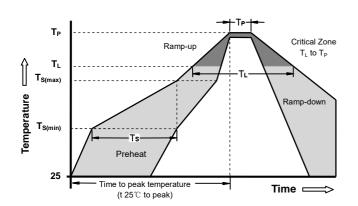
Direction of Unreeling

	Reel	Inner Box	Carton
Size	330×17mm	340×333×70mm	375×353×380mm
Quantity	MPQ/MOQ: 1 reel=2,500pcs	1 Inner Box=4 reels=10,000pcs	1 Carton=5 Inner boxes=50,000pcs
Photos		Party Manager Control of the Control	RULLON   SING PROPERTY OF STREET OF



### SMD3225 Series

# **Soldering Parameters - Reflow Soldering (Surface Mount Devices)**



Reflow Cond	ition	Pb - Free assembly		
	-Temperature Min (T <sub>s(min)</sub> )	150°C		
Preheat	-Temperature Max (T <sub>s(max)</sub> )	200°C		
	- Time (min to max) (t <sub>s</sub> )	60 -180 Seconds		
Average ram to peak	p up rate ( Liquids Temp T <sub>L</sub> )	3°C/second max		
T <sub>S(max)</sub> to TL -	Ramp-up Rate	5°C/second max		
Reflow	- Temperature (T <sub>L</sub> ) (Liquids)	217°C		
	- Time (min to max) (t <sub>s</sub> )	60 -150 Seconds		
Peak Temper	rature (T <sub>P</sub> )	260 +0/-5°C		
Time within 5	5°C of actual peak (t <sub>p</sub> )	10 - 30 Seconds		

Surface mounted components (SMD) may exhibit a temporary increase in the DC spark-over voltage after the solder reflow process. The components will recover within 24 hours. There is no quality defect nor change in protection levels during the temporary change in DC spark-over voltage.

#### **Terms and definitions**

NO.	Item	Definitions	
		A gap, or several gaps, in an enclosed discharge medium, other than air at atmospheric pressure,	
1	Gas discharge tube(GDT)	designed to protect apparatus or personnel, or both, from high transient voltages. Also referred to as	
		"gas tube surge arrester".	
2	DC Spark-over Voltage	The voltage at which the gas discharge tube sparks over with slowly increasing d.c. voltage.	
3	Impulse Spark-over	The highest voltage which appears across the terminals of a gas discharge tube in the period between	
3	Voltage	the application of an impulse of given wave-shape and the time when current begins to flow.	
5	Arc voltage	Voltage drop across the GDT during arc current flow.	
6	Glow voltage	Peak value of voltage drop across the GDT when a glow current is flowing.	
7	Impulse discharge current 8/20µs	Current impulse with a nominal virtual front time of 8 μs and a nominal time to half-value of 20 μs.	
8	Alternating Discharge Current	The rms value of an approximately sinusoidal alternating current passing through the gas discharge tube.	
9	Insulation Resistance	Insulation resistance shall be measured from each terminal to every other terminal of the GDT. The test is performed with DC50V when normal spark-over Voltage 70~150V, others with DC100V.	
10	Capacitance	The capacitance shall be measured once at 1 MHz between all terminals unless otherwise specified.	





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#### **Cautions and warnings**

- I Do not operate surge arresters in power supply networks, whose maximum operating voltage exceeds the minimum spark-over voltage of the surge arresters.
- I Surge arresters may become hot in the event of longer periods of current stress (burn risk). In the event of overload the connectors may fail or the component may be destroyed.
- I Surge arresters must be handled with care and must not be dropped.
- I Do not continue to use damaged surge arresters.
- I The shown SMD pad dimensions represent a safe way to mount the arrester and are a recommendation of the manufacturer.

  During the reflow process it must be assured that no solder material reduces the insulation distance between the pads below the arrester.

Version: A4/2024-08-19

File Number: SP-GDT-003

I SMD surge arresters should be soldered within 24 month after shipment.